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AMENDMENTS TO THE CLAIMS**1-20. (Cancelled)****21. (New)** A piezoelectric resonator element package, comprising:

a base that holds a piezoelectric resonator element on an internal bottom surface of the base, the piezoelectric resonator element having drive electrodes formed on front and back sides of the piezoelectric resonator element and being arranged such that one of the drive electrodes is opposed to the internal bottom surface of the base; and

a cap for hermetically sealing the piezoelectric resonator element,

wherein the base includes four electrode pads that electrically connect to the drive electrodes of the piezoelectric resonator element, each of the four electrode pads being formed on a respective corner of the internal bottom surface of the base, the four electrode pads consisting of a first electrode pad, a second electrode pad, a third electrode pad, and a fourth electrode pad,

wherein the first electrode pad and the second electrode pad are formed along a predetermined side of the internal bottom surface of the base,

the first electrode pad and the third electrode pad are formed along one of two sides that are perpendicular to the predetermined side,

the second electrode pad and the fourth electrode pad are formed along the other of the two sides that are perpendicular to the predetermined side,

the first electrode pad and the second electrode pad have a different potential,

the first electrode pad and the third electrode pad are connected by a first connecting electrode and have a same potential,

the second electrode pad and the fourth electrode pad are connected by a second connecting electrode and have a same potential,

and wherein avoidance means is provided for avoiding electrical connection between at least one of the first and third electrode pads with at least one of the second and fourth electrode pads, the avoidance means comprising bumps that are formed on the four electrode pads and that are smaller than the electrode pads, at least one of the bumps being formed at a location that does not overlap with the drive electrode that is opposed to the internal bottom surface of the base.

22. (New) The piezoelectric resonator element package according to Claim 21, wherein the base is composed of a ceramic material, and the electrode pads are formed by metallization, and the bumps are formed of a same material as the electrode pads.

23. (New) The piezoelectric resonator element package according to Claim 22, wherein the electrode pads, the bumps, and the first and second connecting electrodes are formed in point symmetry, with a center point being a center of the internal bottom surface of the base.

24. (New) The piezoelectric resonator element package according to Claim 23, wherein the first connecting electrode and the second connecting electrode are formed with a substantially same area capacity.

25. (New) A piezoelectric resonator, provided with the piezoelectric resonator element package according to Claim 23 and a piezoelectric resonator element having drive electrodes formed on front and back sides of the piezoelectric resonator element, wherein the piezoelectric resonator element is held on the internal bottom surface of the base, and the electrode pads of the base and the drive electrodes of the piezoelectric resonator element are electrically connected.

26. (New) The piezoelectric resonator element package according to Claim 22, wherein the first connecting electrode and the second connecting electrode are formed with a substantially same area capacity.

27. (New) A piezoelectric resonator, provided with the piezoelectric resonator element package according to Claim 22 and a piezoelectric resonator element having drive electrodes formed on front and back sides of the piezoelectric resonator element, wherein the piezoelectric resonator element is held on the internal bottom surface of the

base, and the electrode pads of the base and the drive electrodes of the piezoelectric resonator element are electrically connected.

28. (New) The piezoelectric resonator element package according to Claim 21, wherein the electrode pads, the bumps, and the first and second connecting electrodes are formed in point symmetry, with a center point being a center of the internal bottom surface of the base.

29. (New) The piezoelectric resonator element package according to Claim 28, wherein the first connecting electrode and the second connecting electrode are formed with a substantially same area capacity.

30. (New) A piezoelectric resonator, provided with the piezoelectric resonator element package according to Claim 28 and a piezoelectric resonator element having drive electrodes formed on front and back sides of the piezoelectric resonator element, wherein the piezoelectric resonator element is held on the internal bottom surface of the base, and the electrode pads of the base and the drive electrodes of the piezoelectric resonator element are electrically connected.

31. (New) The piezoelectric resonator element package according to Claim 21, wherein the first connecting electrode and the second connecting electrode are formed with a substantially same area capacity.

32. (New) A piezoelectric resonator, provided with the piezoelectric resonator element package according to Claim 21 and a piezoelectric resonator element having drive electrodes formed on front and back sides of the piezoelectric resonator element, wherein the piezoelectric resonator element is held on the internal bottom surface of the base, and the electrode pads of the base and the drive electrodes of the piezoelectric resonator element are electrically connected.

33. (New) The piezoelectric resonator according to Claim 32, further comprising:

a front-side extraction electrode that is extracted from one of the drive electrodes to two end regions at a predetermined end of the piezoelectric resonator element, the front-side extraction electrode being formed on the front side of the piezoelectric resonator element; and

a back-side extraction electrode that is extracted from one of the drive electrodes to two end regions at an end of the piezoelectric resonator element opposite from the predetermined end of the piezoelectric resonator element, the back-side extraction electrode being formed on the back side of the piezoelectric resonator element,

wherein the front-side extraction electrode is electrically connected to at least one of the electrode pads, and

the back-side extraction electrode is electrically connected to at least one of the electrode pads which has a different potential from that of the at least one of the electrode pads electrically connected to the front-side extraction electrode.

34. (New) A piezoelectric resonator element package, comprising:

a base that holds a piezoelectric resonator element on an internal bottom surface of the base, the piezoelectric resonator element having drive electrodes formed on front and back sides of the piezoelectric resonator element; and

a cap for hermetically sealing the piezoelectric resonator element,

wherein the base includes four electrode pads that electrically connect to the drive electrodes of the piezoelectric resonator element, each of the four electrode pads being formed on a respective corner of the internal bottom surface of the base, the four electrode pads consisting of a first electrode pad, a second electrode pad, a third electrode pad, and a fourth electrode pad,

wherein the first electrode pad and the second electrode pad are formed along a predetermined side of the internal bottom surface of the base,

the first electrode pad and the third electrode pad are formed along one of two sides that are perpendicular to the predetermined side,

the second electrode pad and the fourth electrode pad are formed along the other of the

two sides that are perpendicular to the predetermined side,
the first electrode pad and the second electrode pad have a different potential,
the first electrode pad and the third electrode pad are connected by a first connecting electrode and have a same potential,
the second electrode pad and the fourth electrode pad are connected by a second connecting electrode and have a same potential,
and wherein avoidance means is provided for avoiding electrical connection between at least one of the first and third electrode pads with at least one of the second and fourth electrode pads, the avoidance means being configured such that four electrode pad formation regions are formed in corners of the internal bottom surface of the base for the formation of the four electrode pads, respectively, wherein an area capacity of each of the electrode pads fits within a corresponding one of the four electrode pad formation regions, and the area capacity of at least one of the electrode pads is set to be less than the area capacity of the other electrode pads.

35. (New) The piezoelectric resonator element package according to Claim 34,
wherein the at least one of the electrode pads with the lesser area capacity is formed away from the other electrode pad formation regions within the corresponding electrode pad formation region in which the at least one of the electrode pads with the lesser area capacity is formed.

36. (New) The piezoelectric resonator element package according to Claim 35,
wherein the first connecting electrode and the second connecting electrode are formed with a substantially same area capacity.

37. (New) The piezoelectric resonator element package according to Claim 34,
wherein the first connecting electrode and the second connecting electrode are formed with a substantially same area capacity.

38. (New) A piezoelectric resonator, provided with the piezoelectric resonator element package according to Claim 34 and a piezoelectric resonator element having drive electrodes

formed on front and back sides of the piezoelectric resonator element,

wherein the piezoelectric resonator element is held on the internal bottom surface of the base, and the electrode pads of the base and the drive electrodes of the piezoelectric resonator element are electrically connected.